86100C-12A

S E R V I C E N O T E

Supersedes:
86100C-12

86100C Digital Communications Analyzer Mainframe

Serial Numbers: MY45030387/MY47440886, SG45030106/SG47440118

Motherboard board mounting modification improves product reliability related to boot up issues.

Parts Required:
NONE

ADMINISTRATIVE INFORMATION

SERVICE NOTE CLASSIFICATION: **MODIFICATION RECOMMENDED**			
ACTION CATEGORY:	[ ] ON SPECIFIED FAILURE x AGREEABLE TIME	STANDARDS LABOR: 0.5 Hours	
LOCATION CATEGORY:	[ ] CUSTOMER INSTALLABLE [ ] ON-SITE x SERVICE CENTER [ ] CHANNEL PARTNER	SERVICE INVENTORY: [ ] RETURN [ ] SCRAP [ ] SEE TEXT	USED PARTS: [ ] RETURN [ ] SCRAP [ ] SEE TEXT
AVAILABILITY: EOS		NO CHARGE AVAILABLE UNTIL: EOS Date	
AUTHOR: djs		PRODUCT LINE: 8F	
ADDITIONAL INFORMATION: 86100C-12A clarifies that the service note should be performed on all units with the larger foam pad.			

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Agilent Technologies

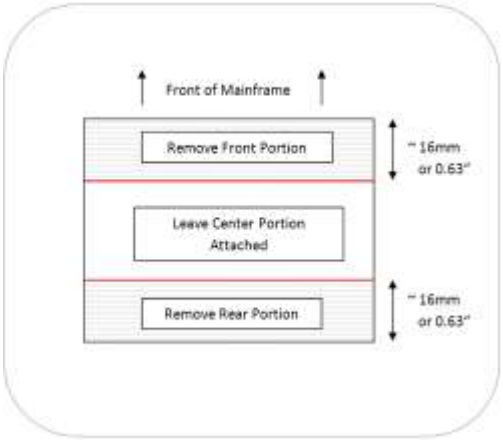
Situation:

Foam mounted underneath the microprocessor board to prevent vibration during shipment may flex the board more than desired on some units, resulting in intermittent power-on failures. Modifying the foam as described reduces the flex and improves reliability.

Solution/Action:

Modify the foam as described below. The modification will remove roughly half of the foam, equally from the front and rear, leaving a strip in the center.

This modification should be completed on all affected 86100C mainframes, even if the unit is not currently showing boot failures.



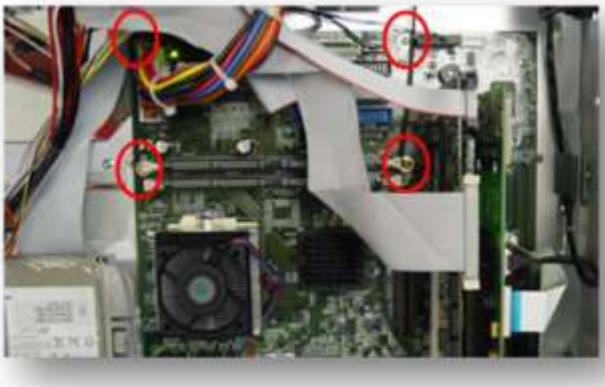
Instructions:

The most common symptom is a boot up error as shown here. The mainframe will come to the point where all LEDs are lighted but will not progress through the boot sequence.

This can be either a hard failure or very intermittent.

To verify the problem is related to the board flexing issue:

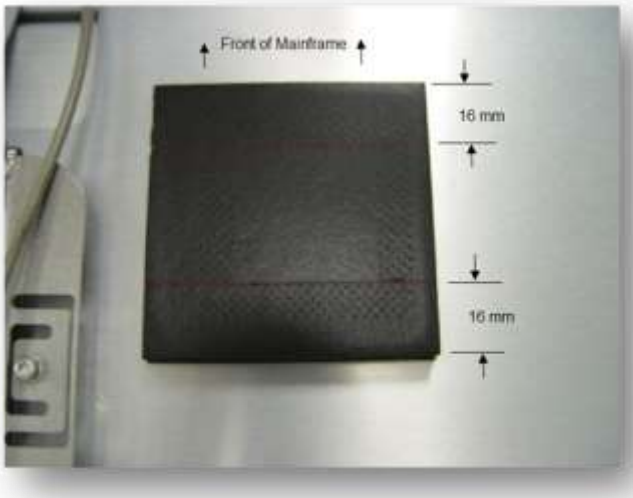
1. Power the instrument off and remove the cover.
2. Loosen the four screws indicated here.
3. Re-boot the instrument.
4. If it boots normally, then board flex caused by the foam is a likely cause.



Instructions (continued):

To modify the mounting foam:

1. Completely remove the mother board and locate the mounting foam underneath the processor. (refer to 86100A/B/C Service Guide for detailed instructions)
2. Use a straight edge and pen to mark the foam with a line approximately 16mm from the front and rear edges of the foam as shown here.



3. Use a knife to cut and remove the front and rear portions leaving the center strip of foam intact.
4. There will be some adhesive left on the mounting tray as shown.
5. Re-install the motherboard and verify proper operation.